

FIG. 1

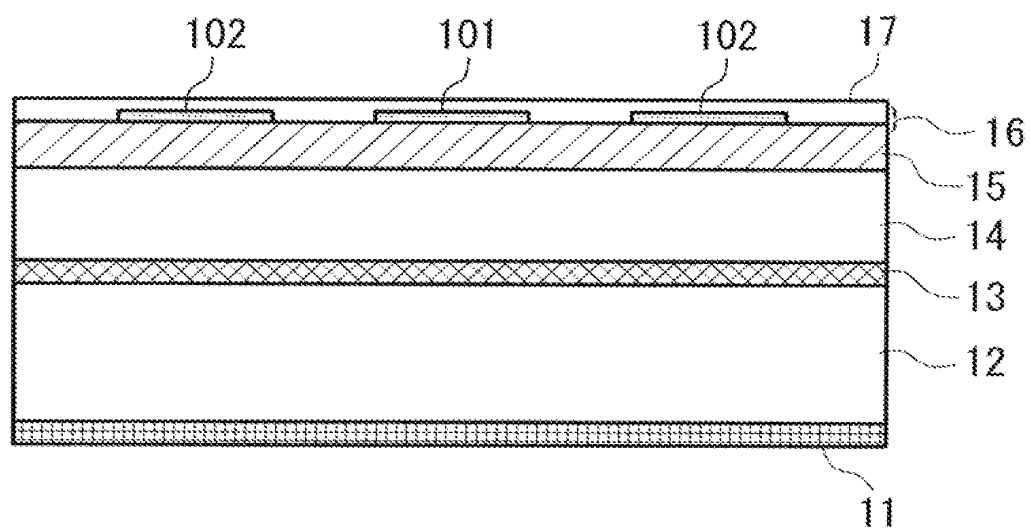


FIG. 2

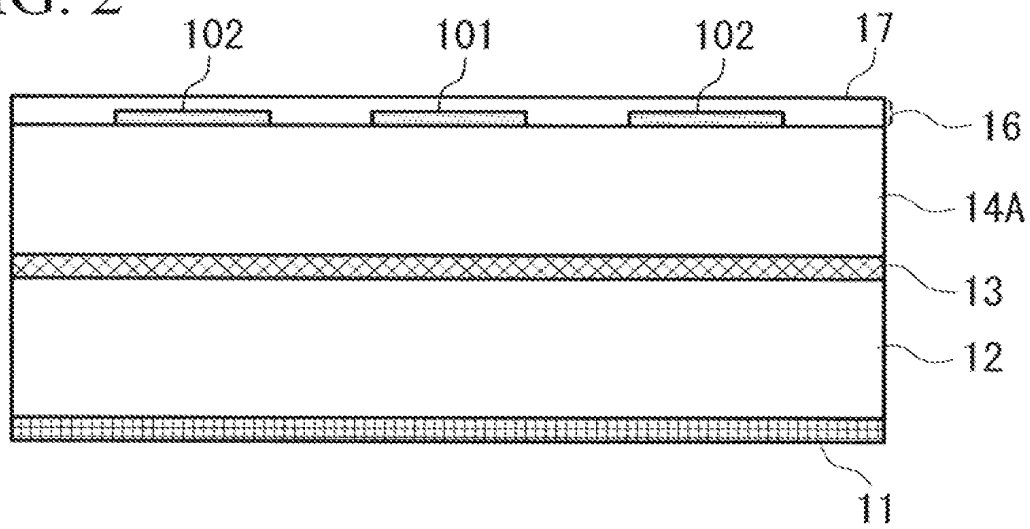


FIG. 3

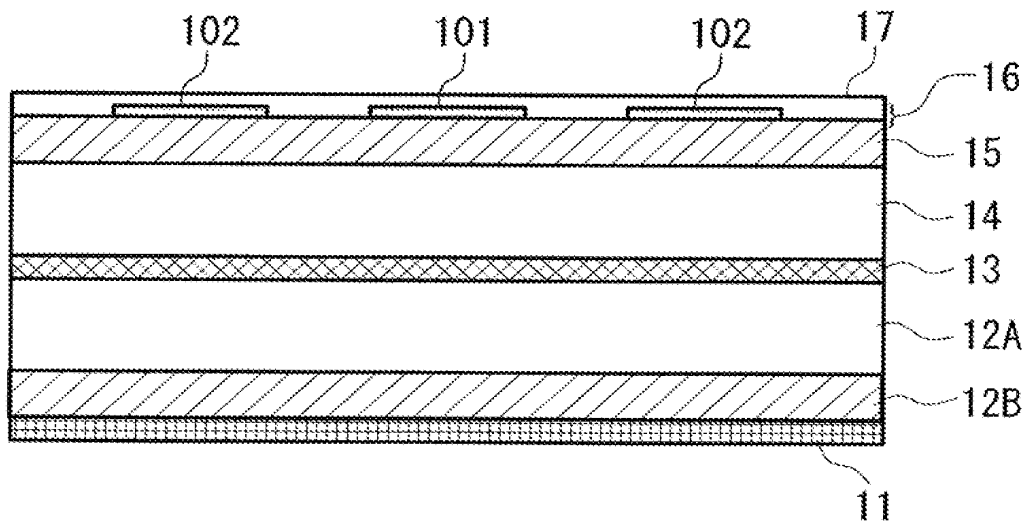


FIG. 4

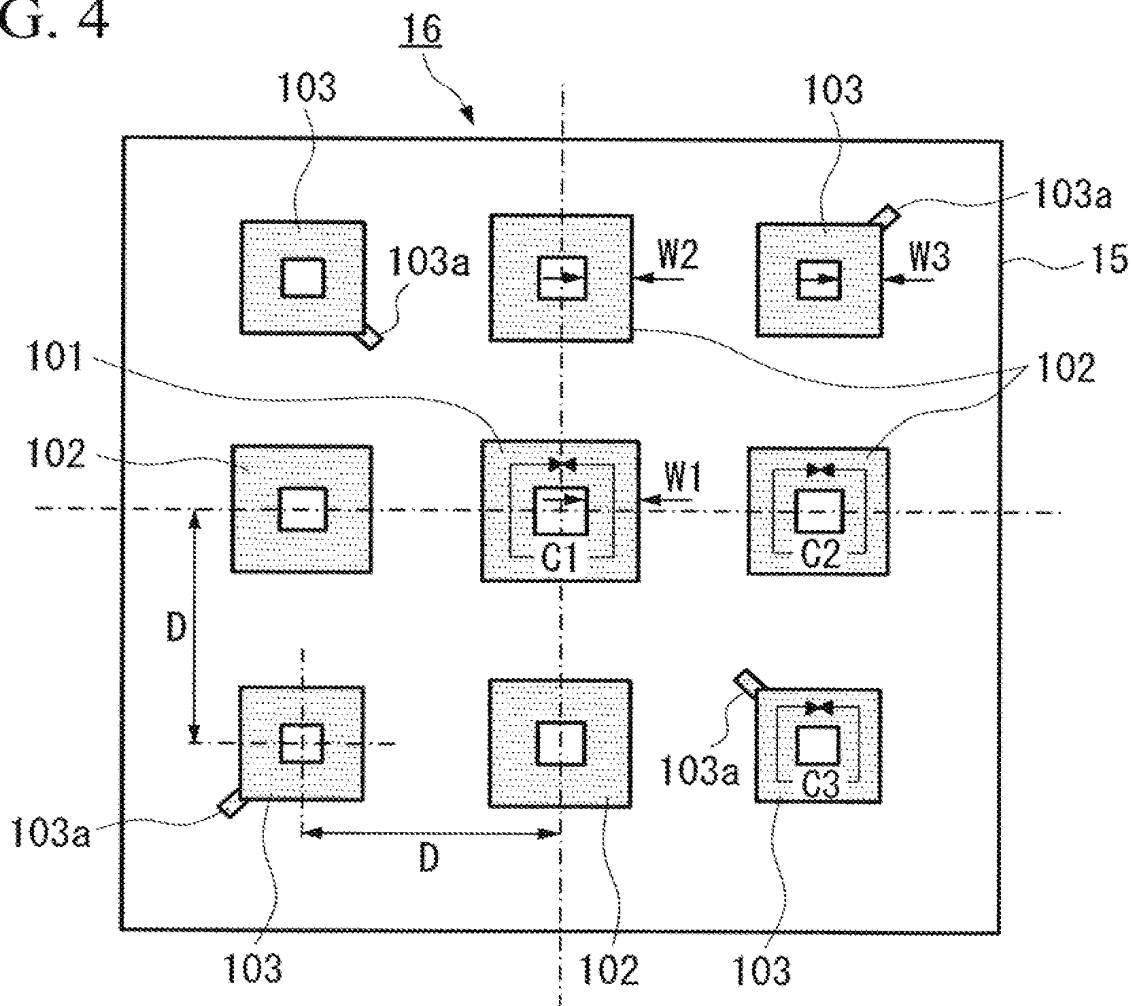


FIG. 5

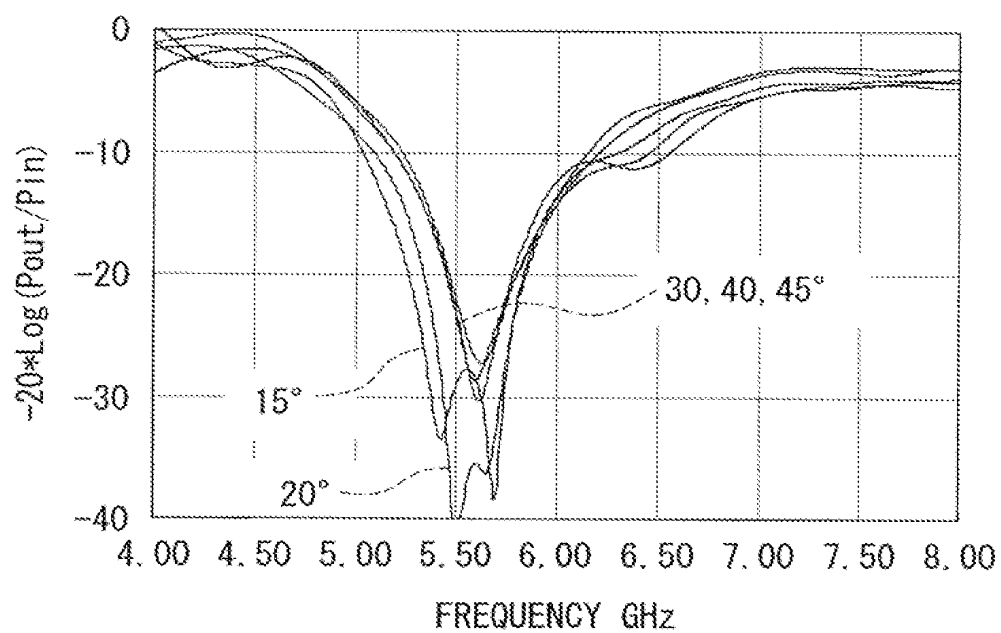


FIG. 6

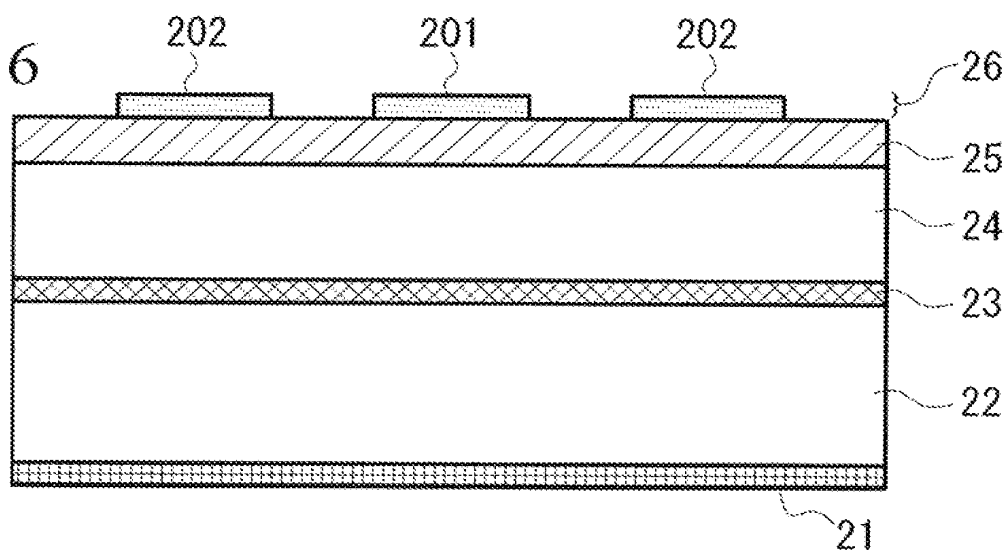


FIG. 7

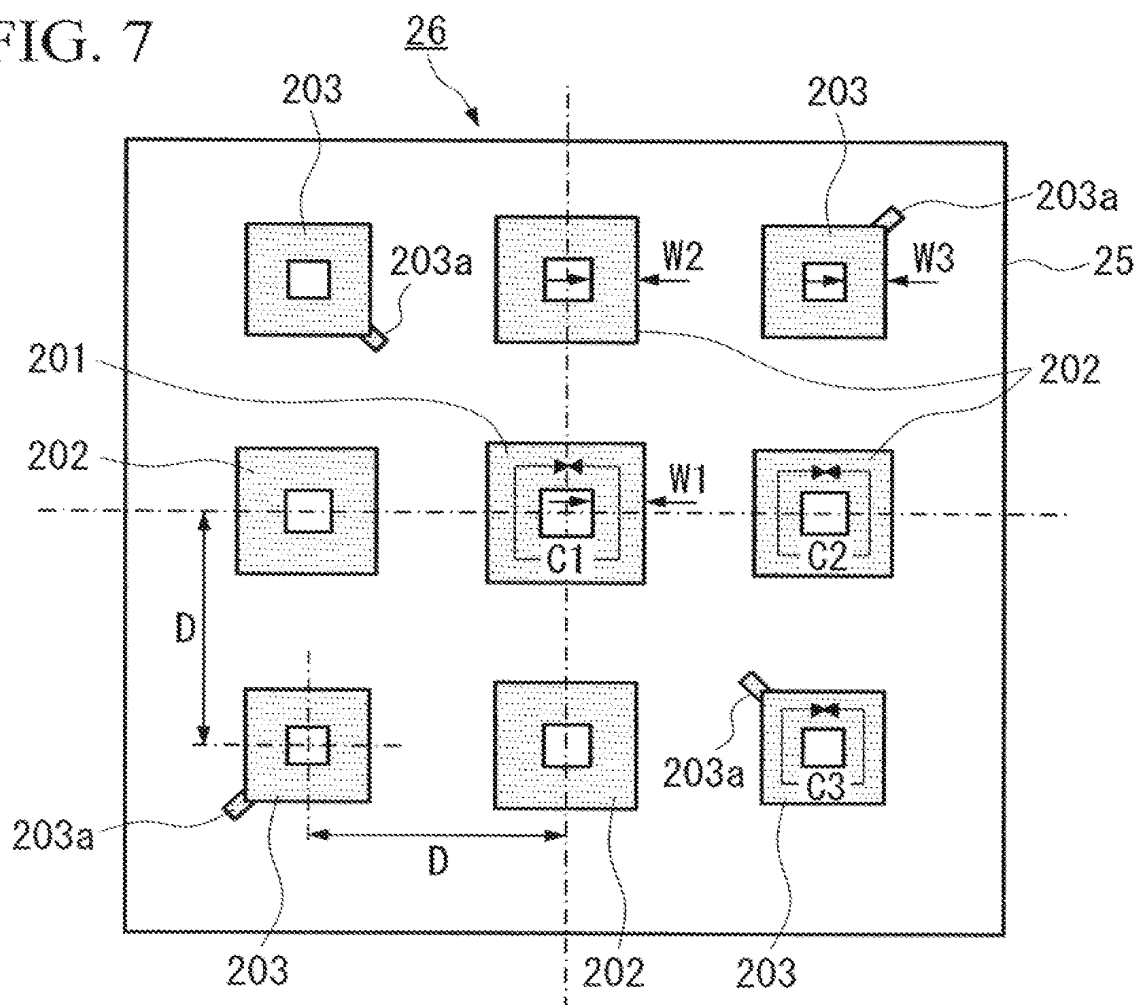


FIG. 8

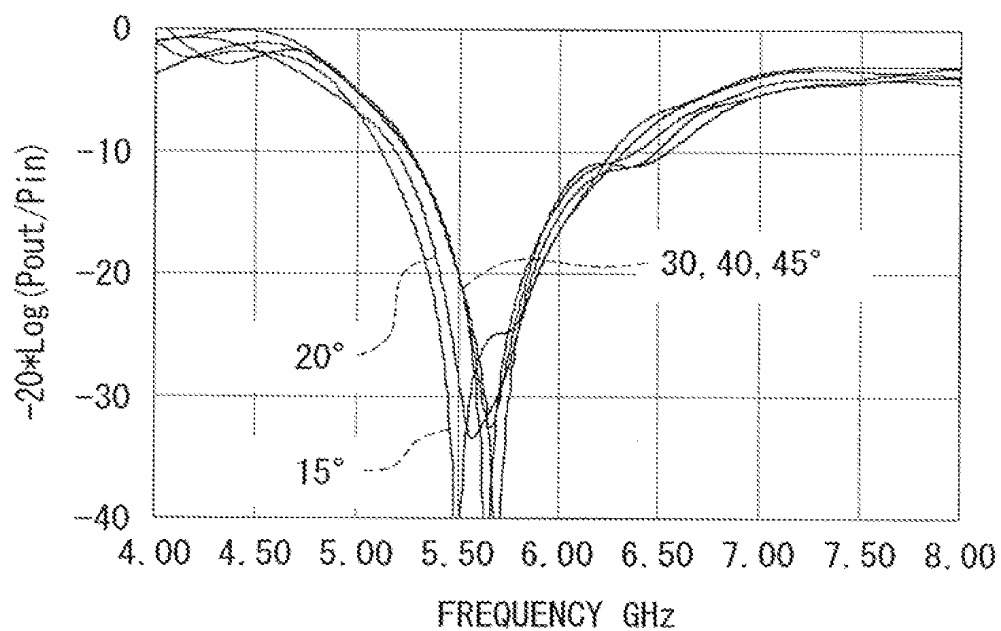


FIG. 9

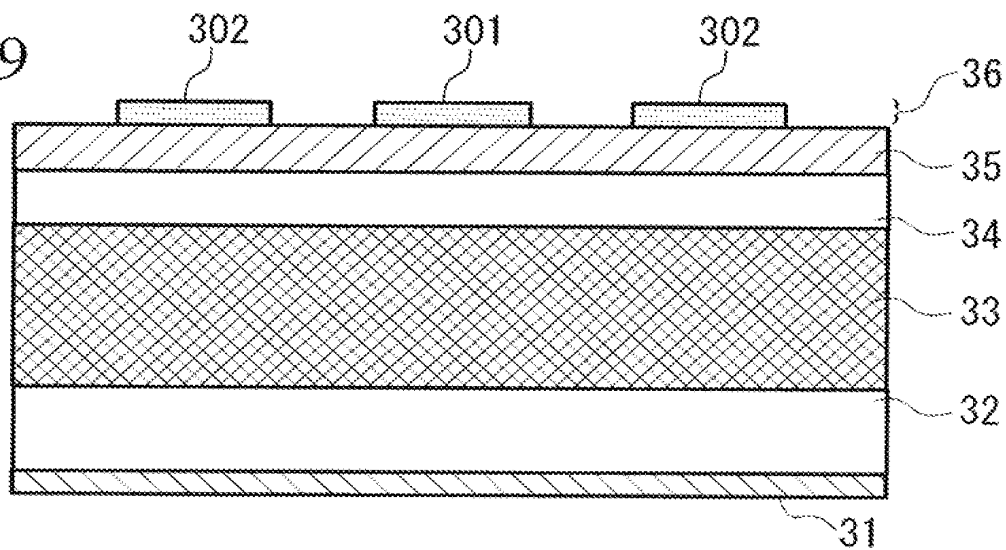


FIG. 10

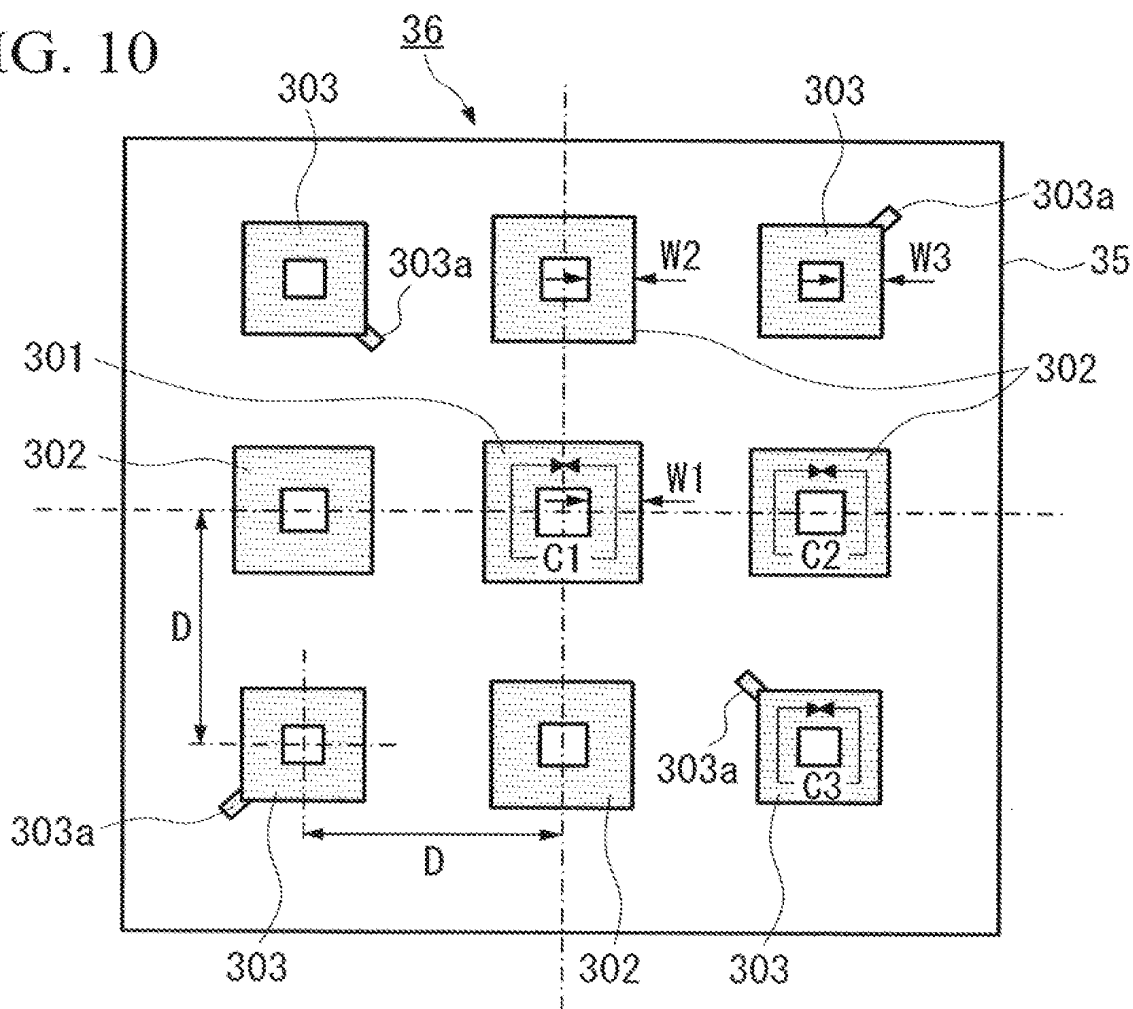


FIG. 11

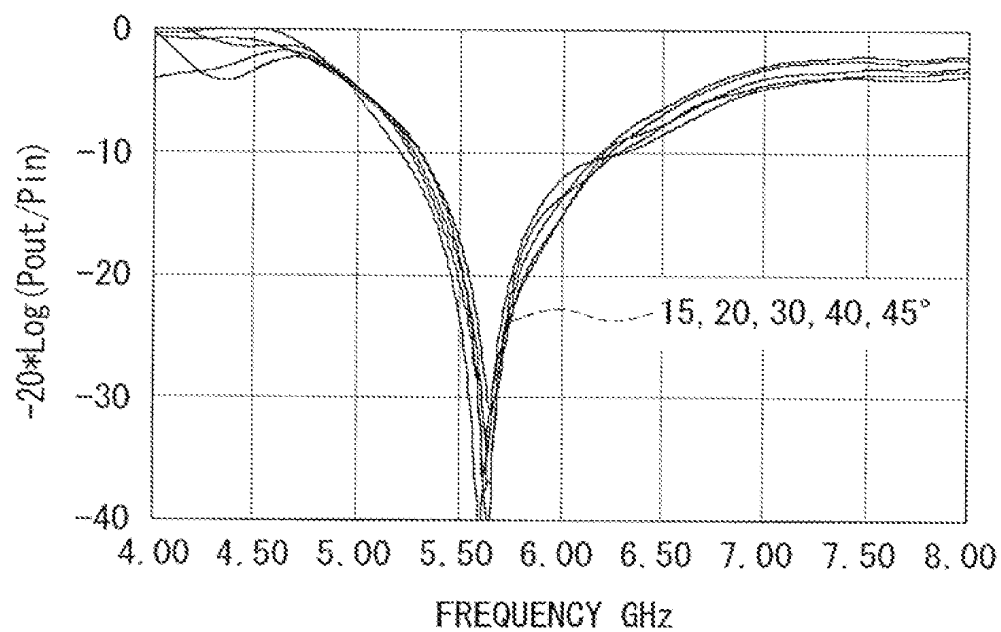


FIG. 12

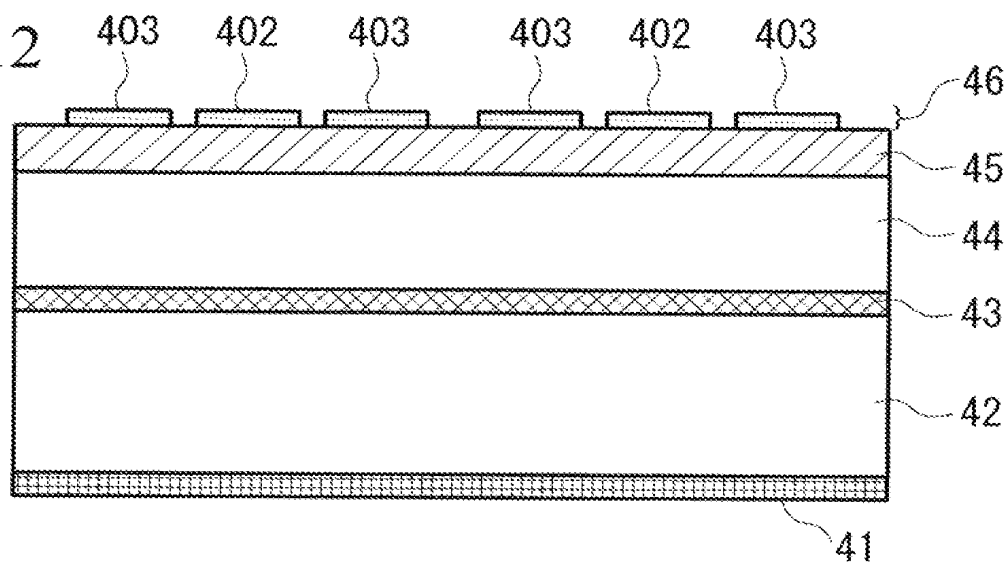
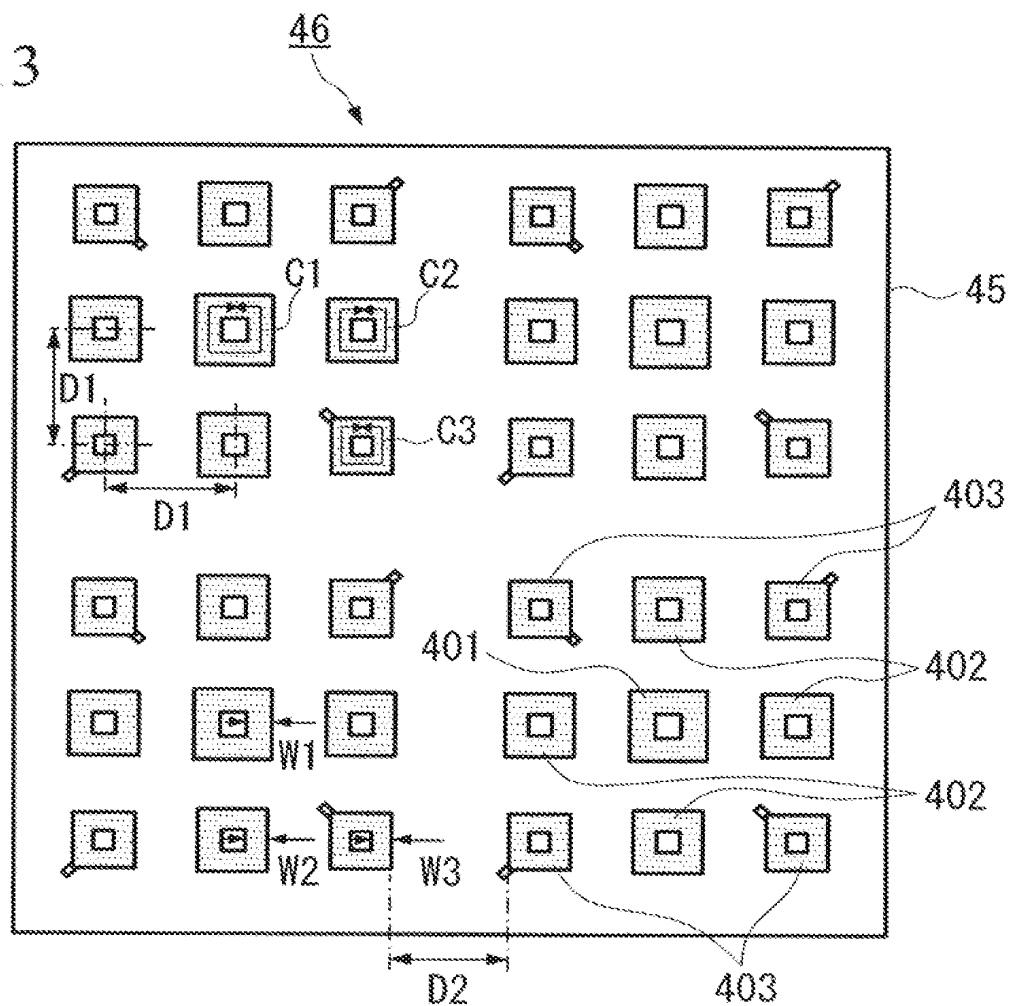


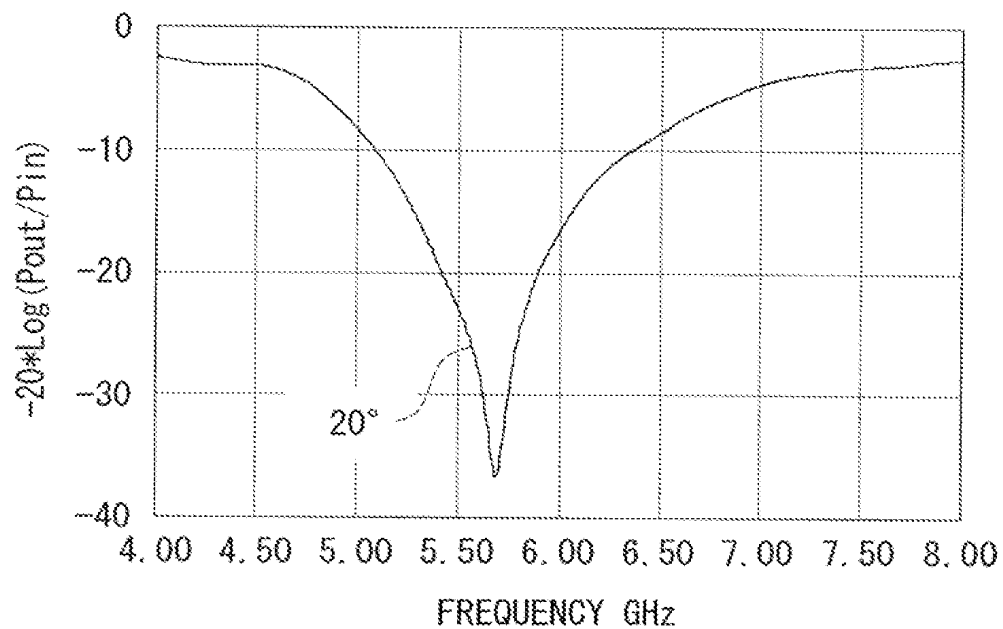
FIG. 13





9/31

FIG. 14



10/31

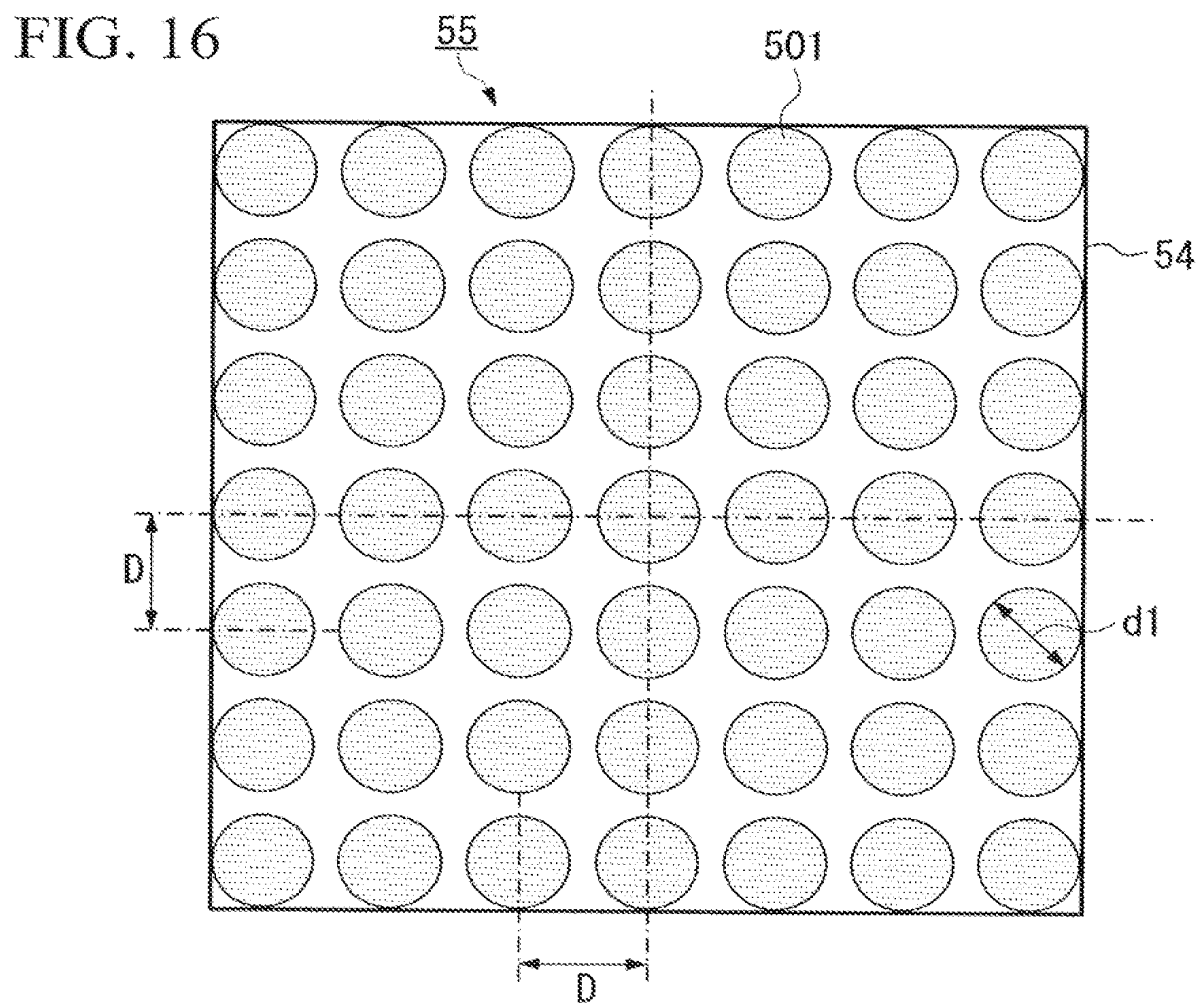
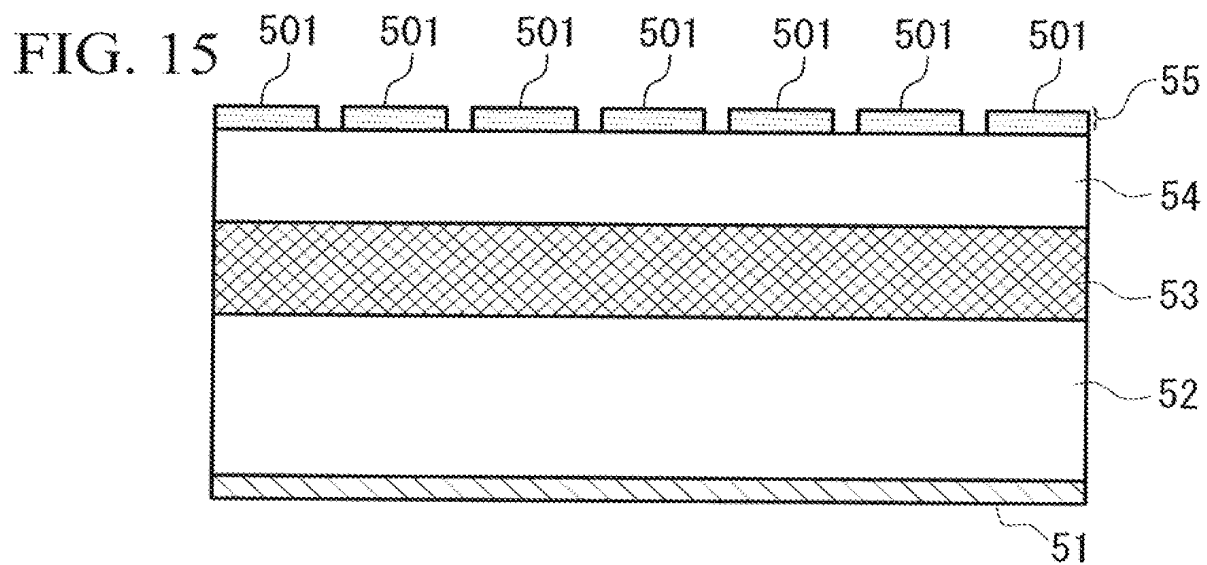
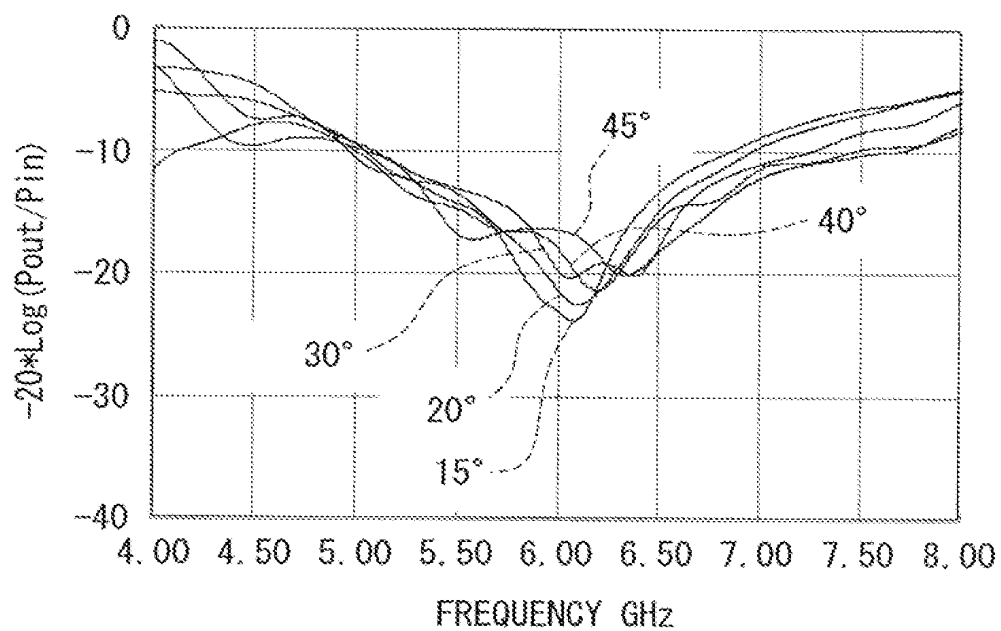


FIG. 17



12/31

FIG. 18

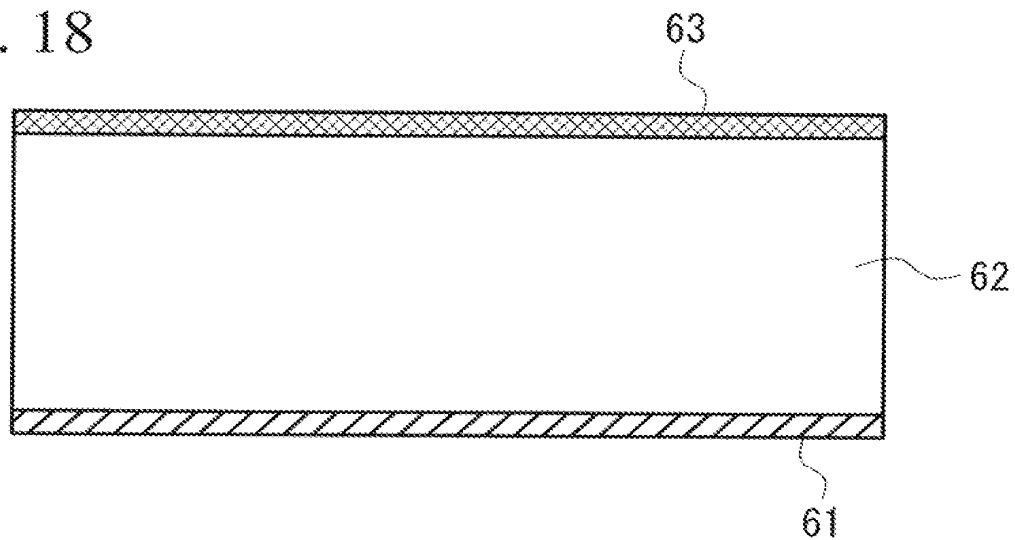
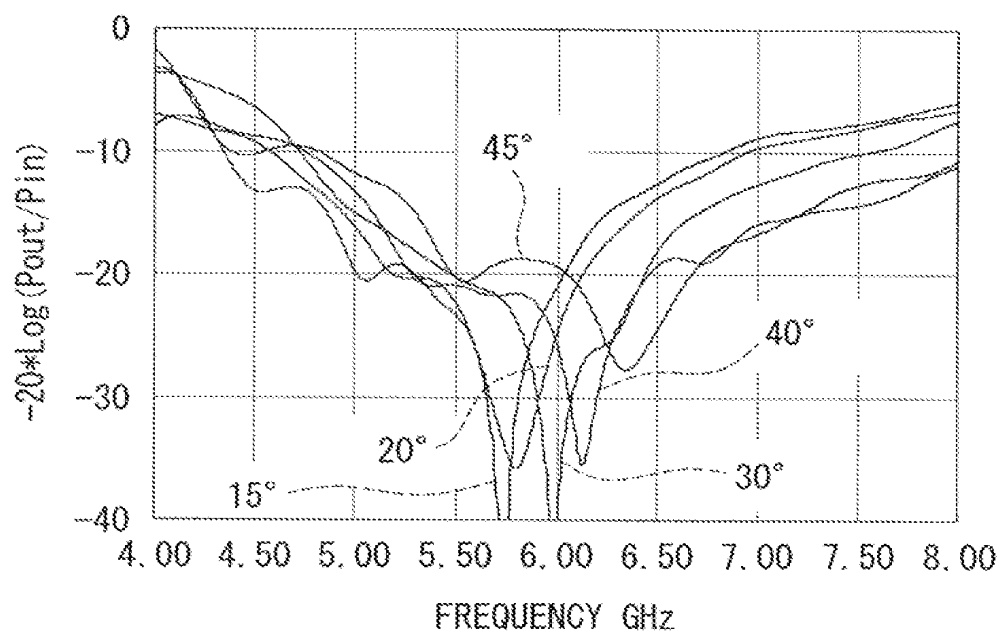


FIG. 19



A cross-sectional view of a semiconductor device 20. The device consists of a substrate 2010 with a bottom layer 2011. Above the bottom layer is a large central region 2012. Above the central region is a thin layer 2014, followed by another thin layer 2015. The top surface of the device features three rectangular regions labeled 2101 and 2102, which are separated by a thin layer 2016.

FIG. 21

2016

2101

2102

2103

W1

C1

D1

D2

FIG. 22

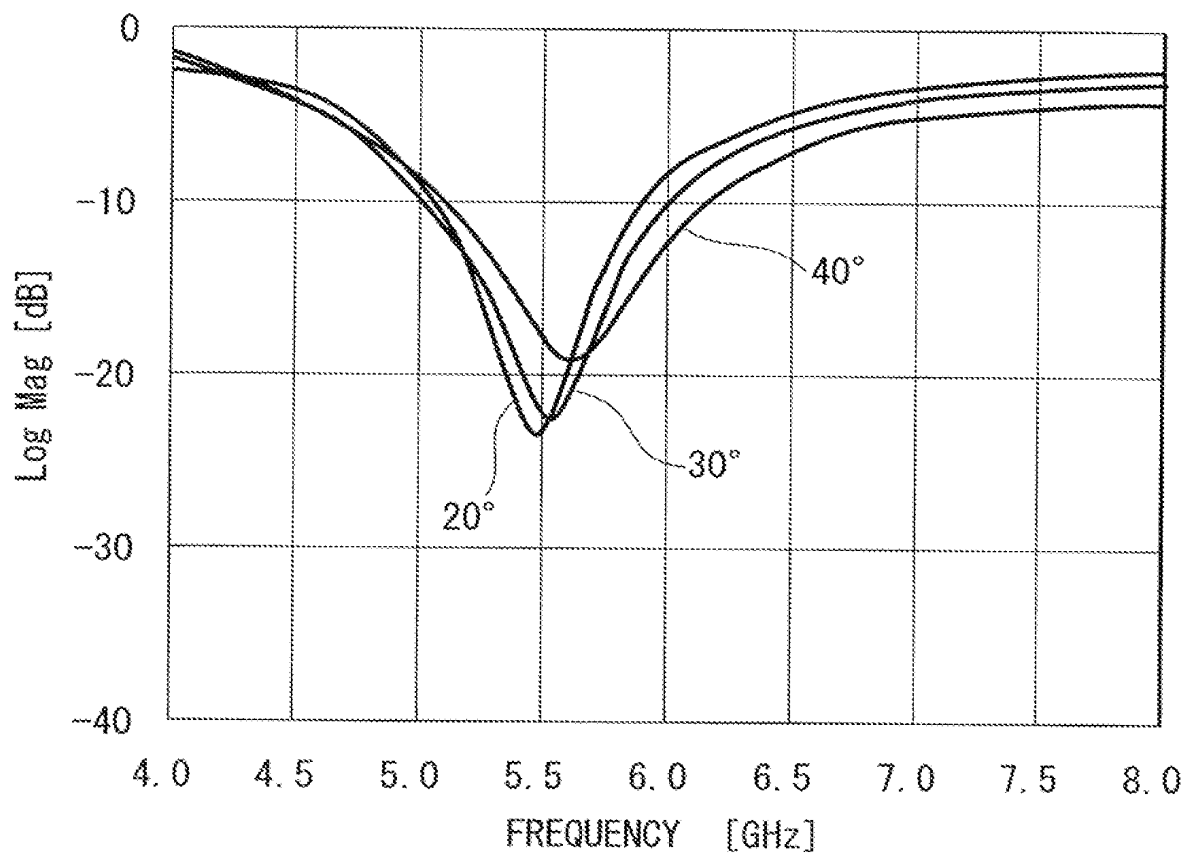


FIG. 24 is a schematic diagram of a 6x6 array of square elements 2203 within a rectangular frame 2027. The elements are arranged in a grid. Some elements have internal features: C1, C2, and C3 are in the second row; W1, W2, and W3 are in the fifth row. Labels 2201, 2202, 2203a, and 2203b point to specific elements or features. Dimensions D1 and D2 are indicated. The frame is labeled 2026.

FIG. 25

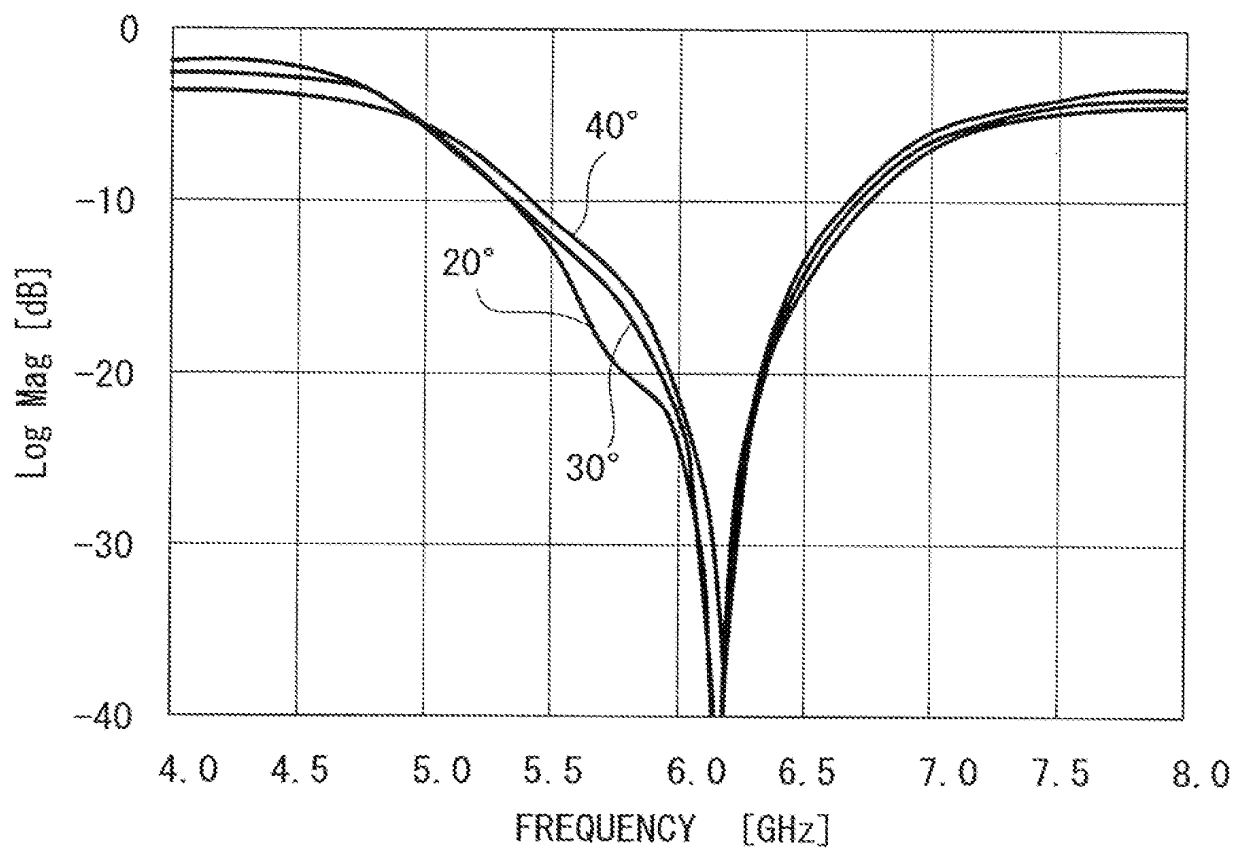
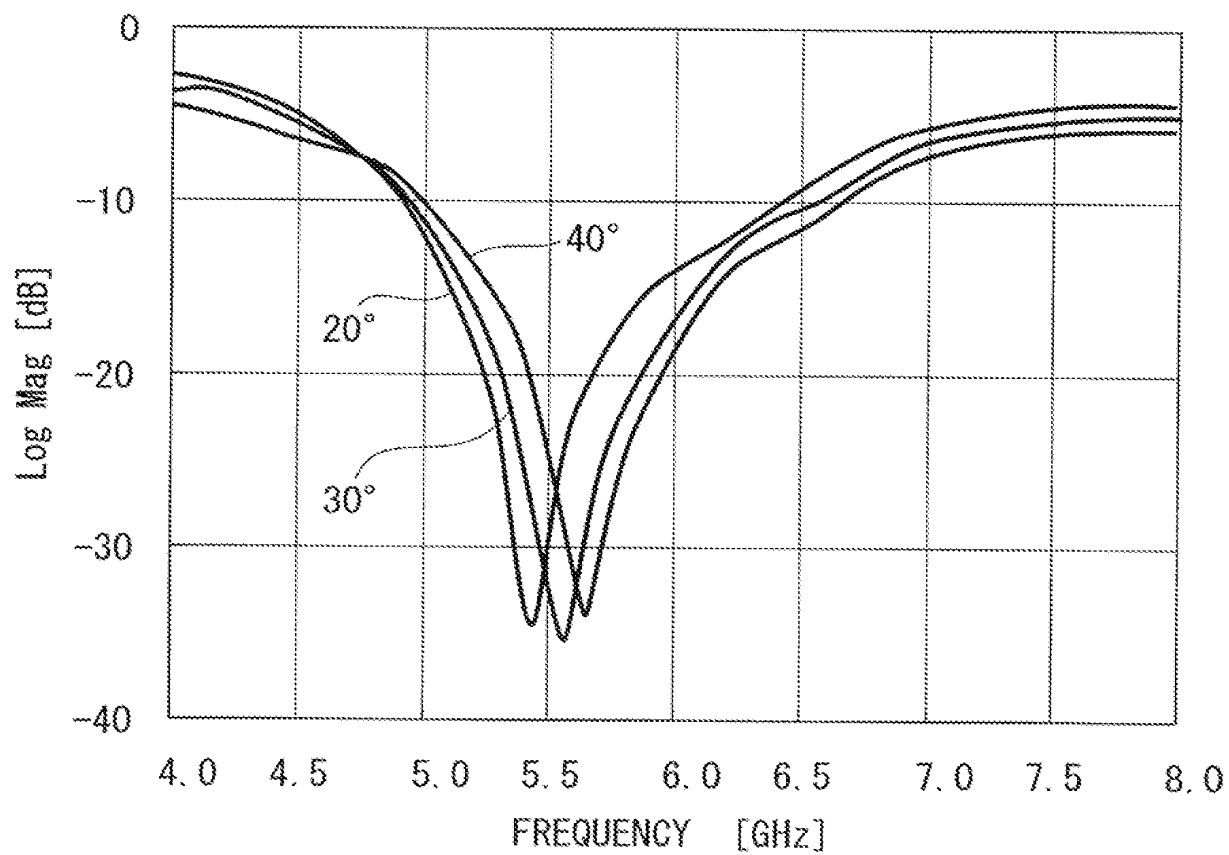




FIG. 27 is a schematic diagram of a 6x6 array of square elements. The array is labeled 2034. Each element consists of a central square (2301) surrounded by a patterned square (2302) and an outer square (2303). The array is labeled 2034. Dimensions D1 and D2 are indicated. Specific elements are labeled C1, C2, C3, and 2303a. Arrows W1, W2, and W3 indicate widths of the central square, the patterned square, and the outer square, respectively.

FIG. 28



[illegible]

FIG. 31

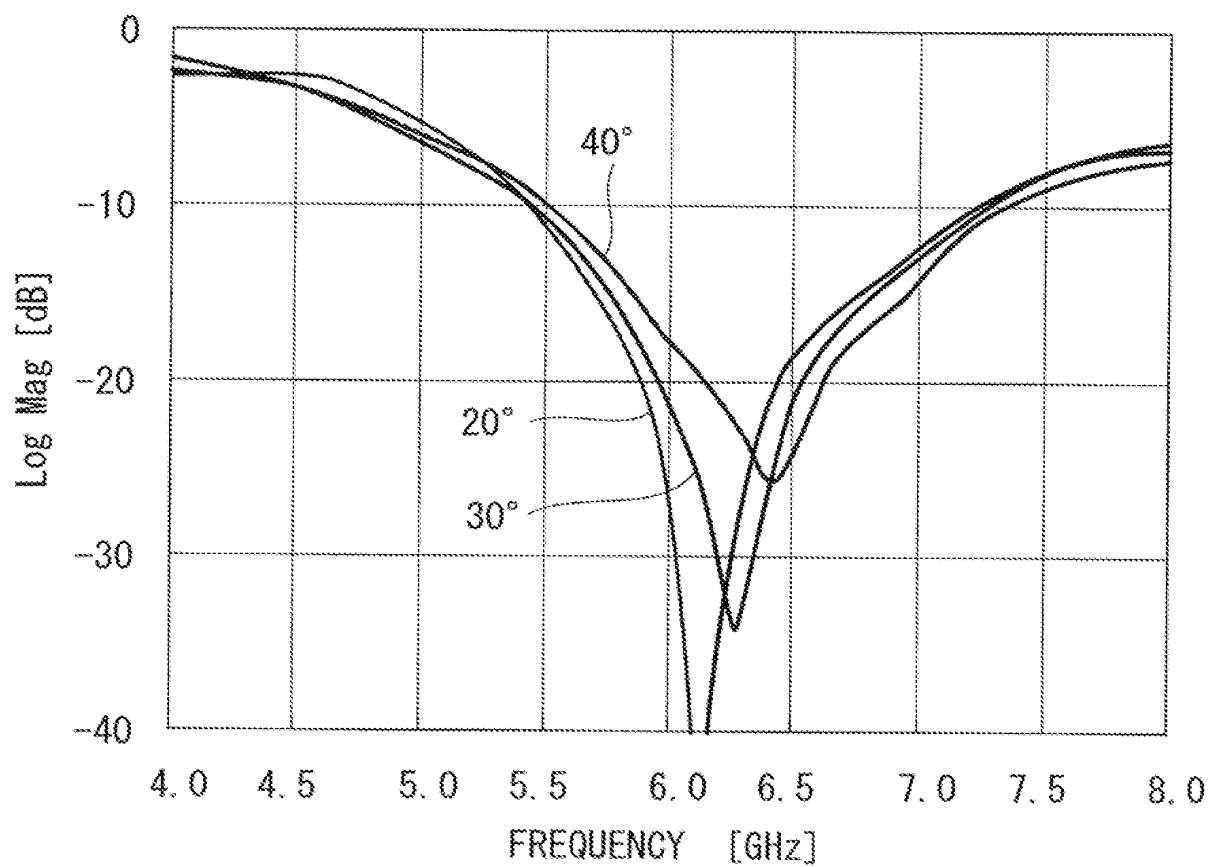


FIG. 32

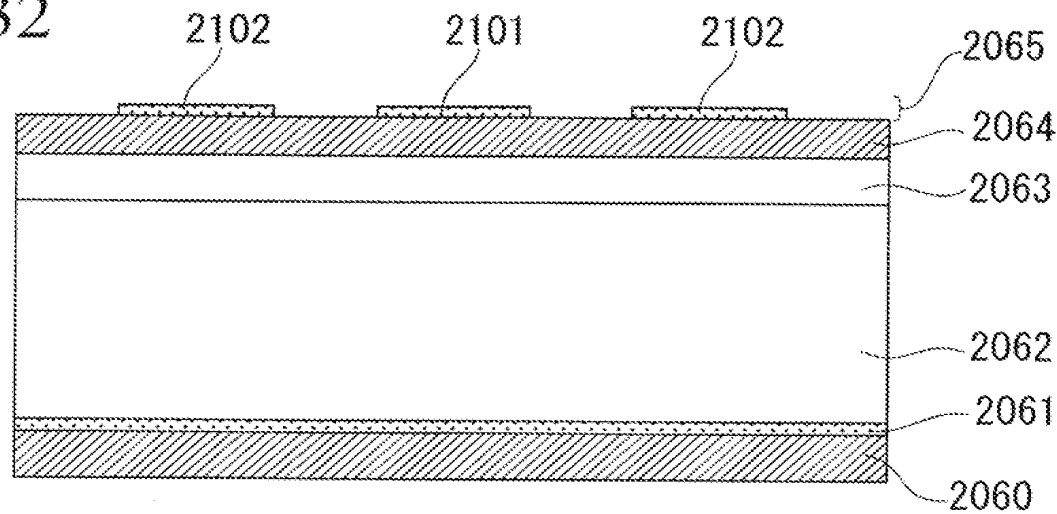
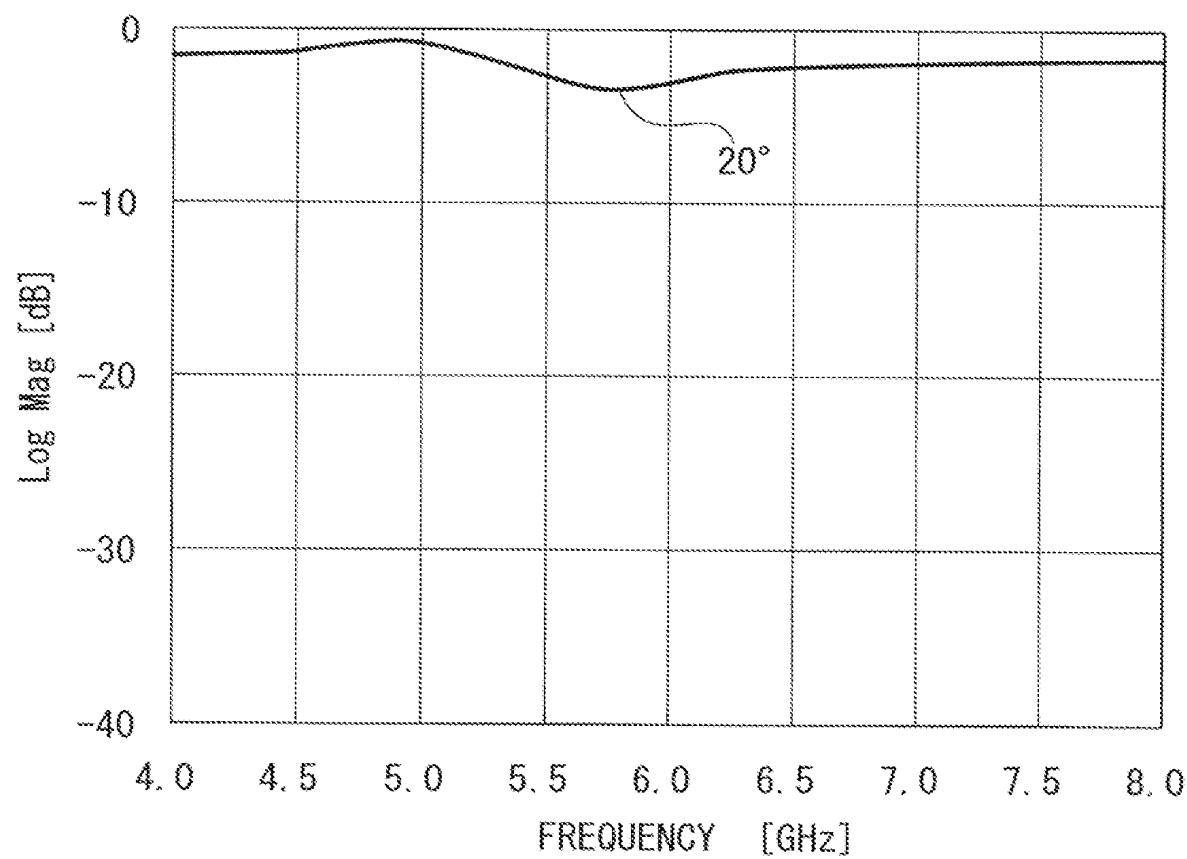


FIG. 33



22/31

FIG. 34

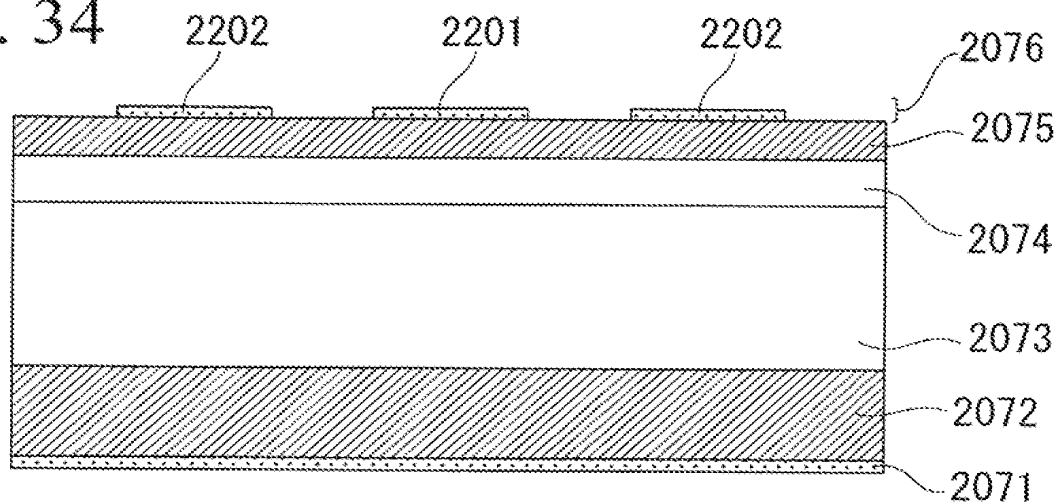
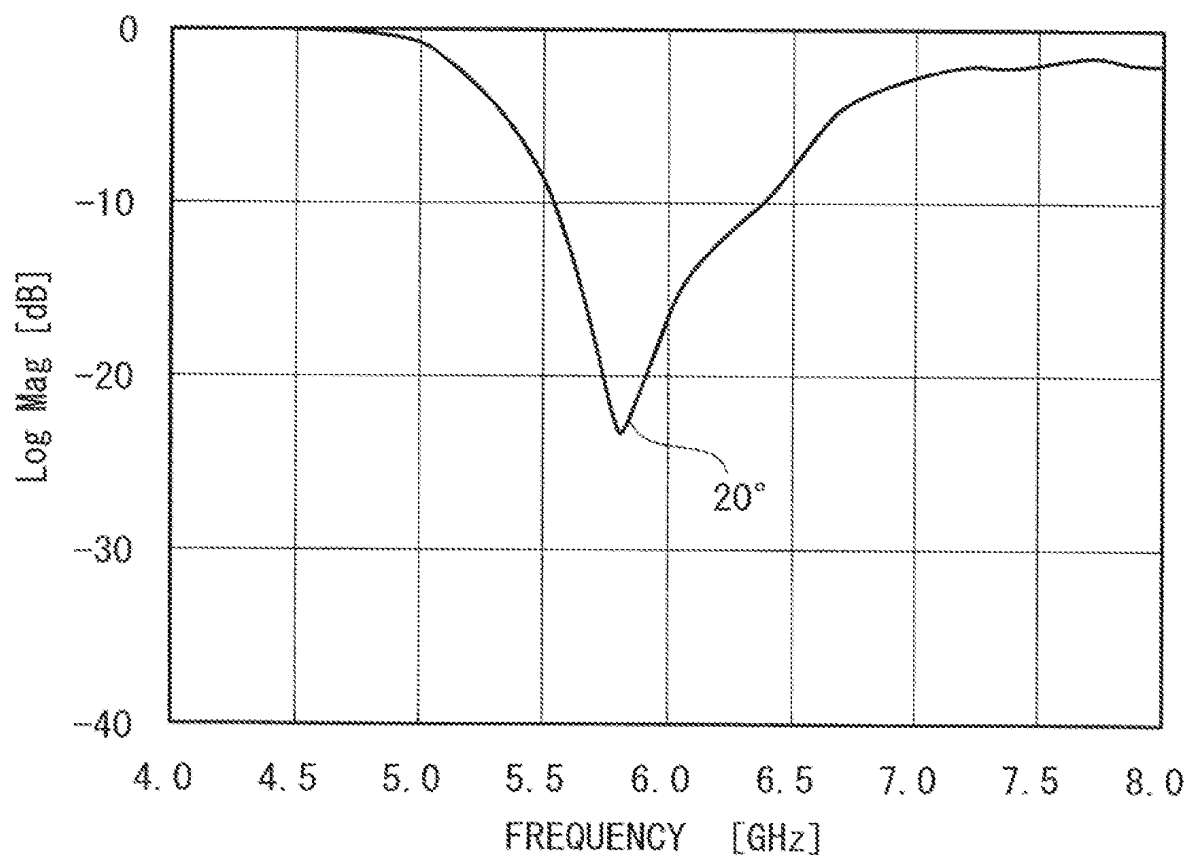


FIG. 35



A cross-sectional view of a substrate assembly 3000. The assembly consists of a substrate 3010 with a top surface 3011 and a bottom surface 3012. A cross-hatched layer 3013 is disposed on the top surface 3011. A layer 3014 is disposed on the cross-hatched layer 3013. A bracket 3015 indicates a region on the top surface 3011 where three rectangular features 3101 and 3102 are located. Features 3101 and 3102 are disposed on the layer 3014.

G. 37

3015

3103a

3103b

3014

3103a

3103

3101

3102

3102

3102

3103

D1

D2

C1

C2

C3

W1

W2

W3

24/31

FIG. 38

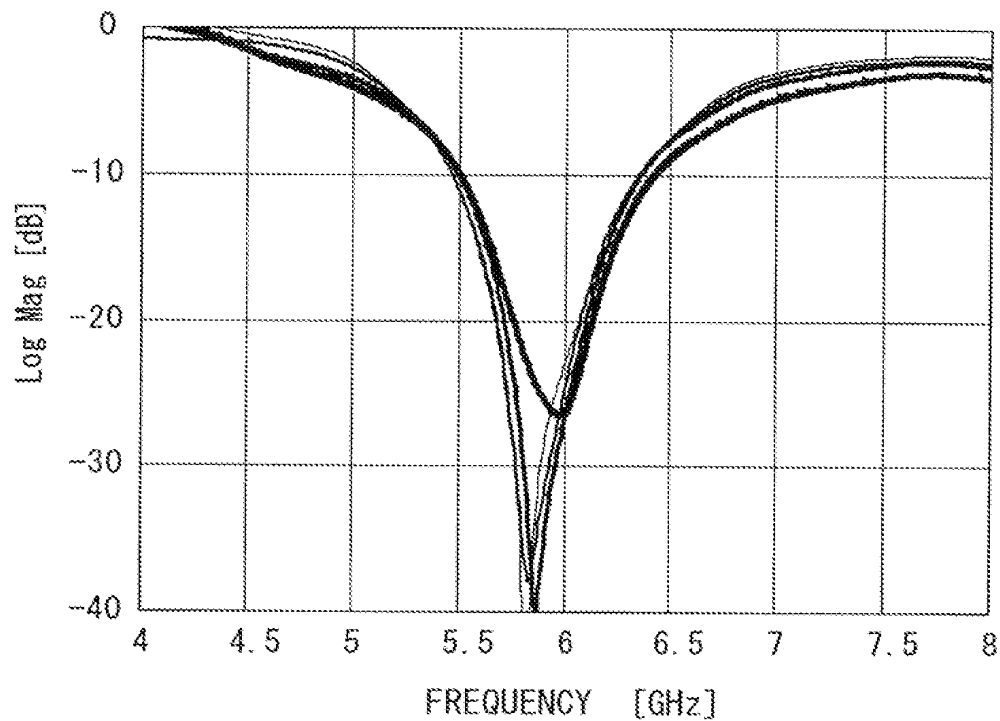


FIG. 39

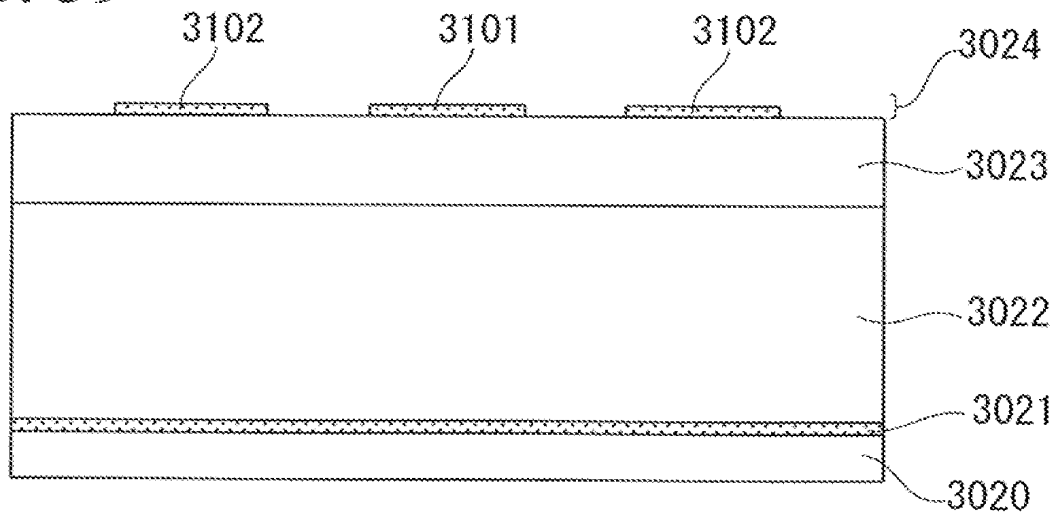
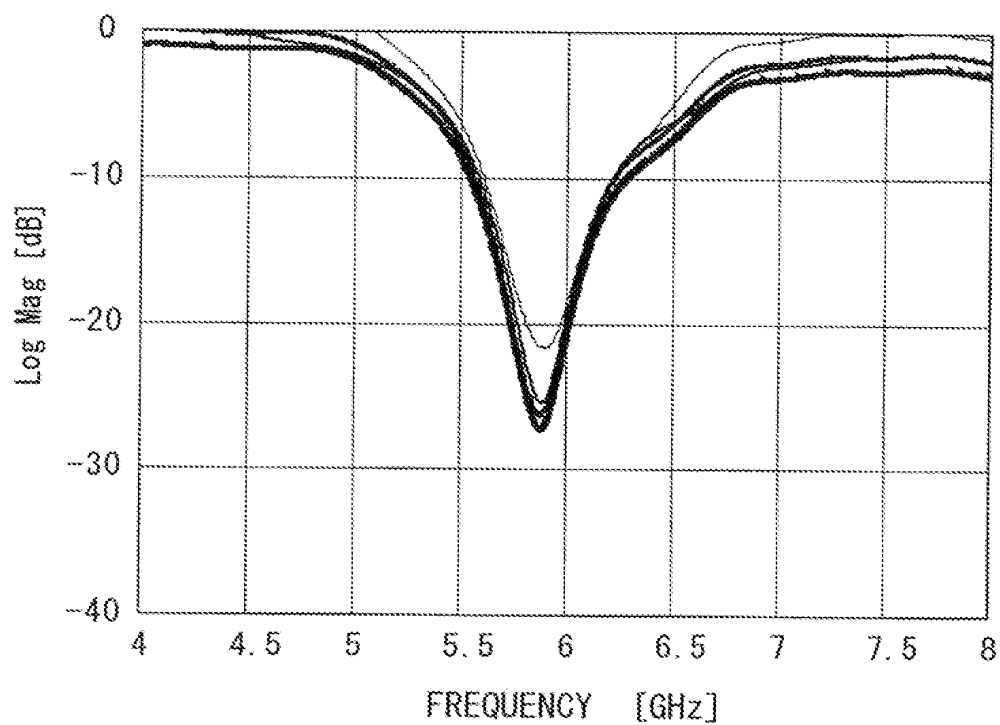




FIG. 40



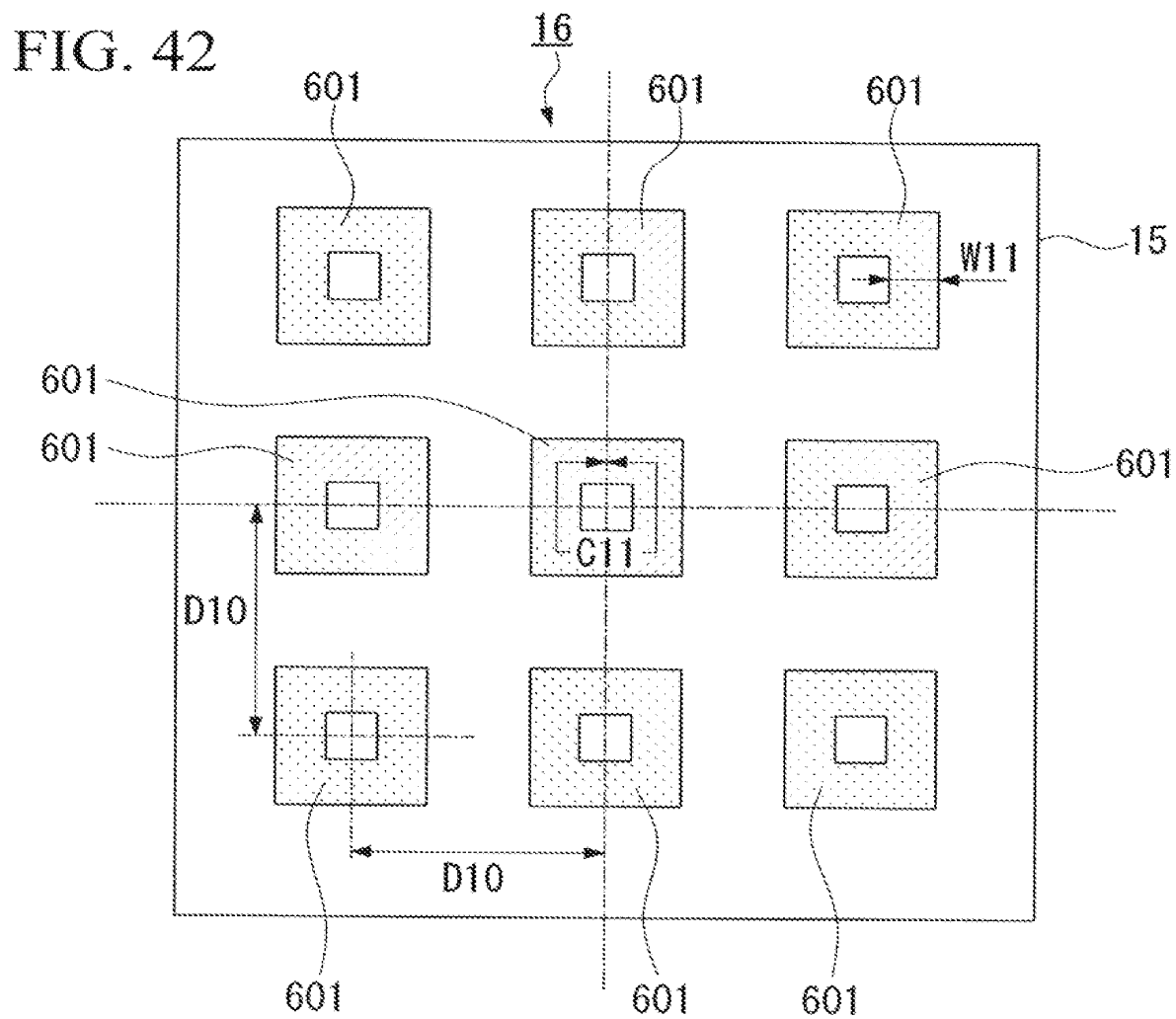
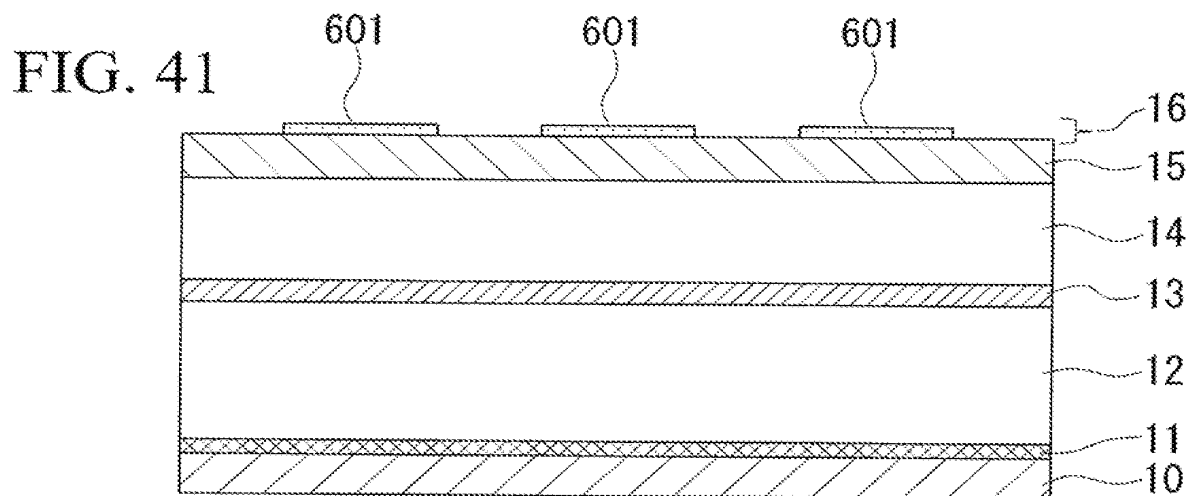
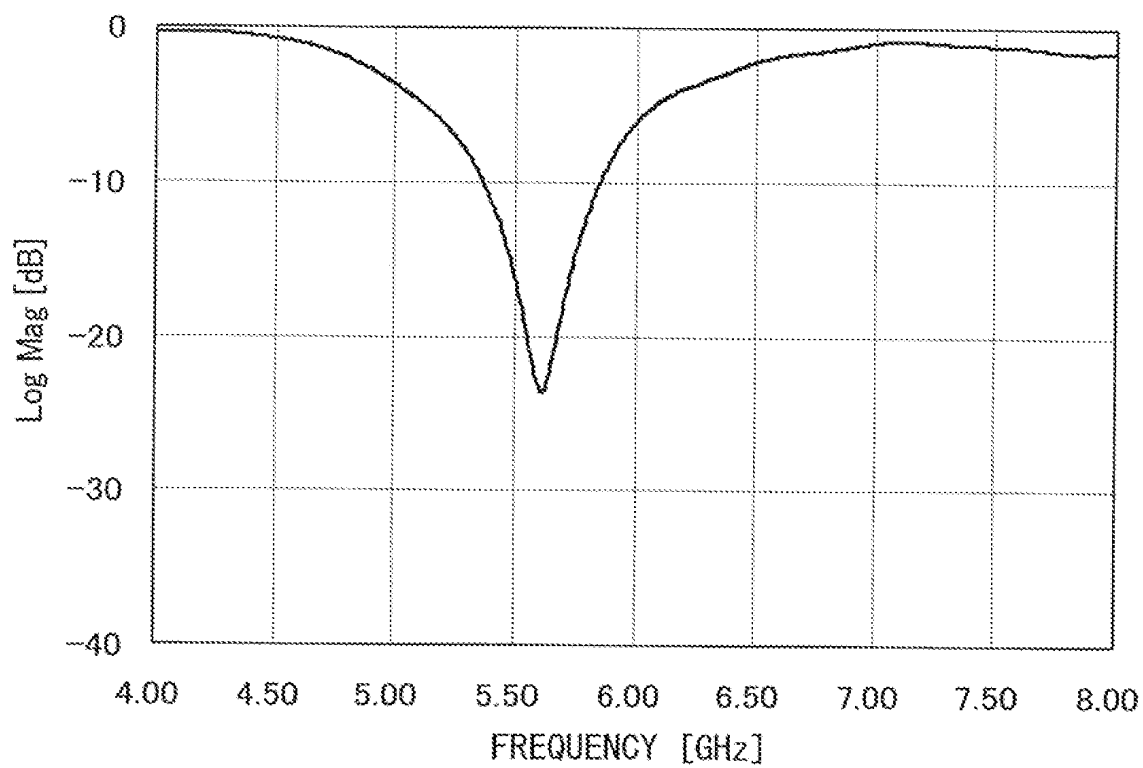


FIG. 43



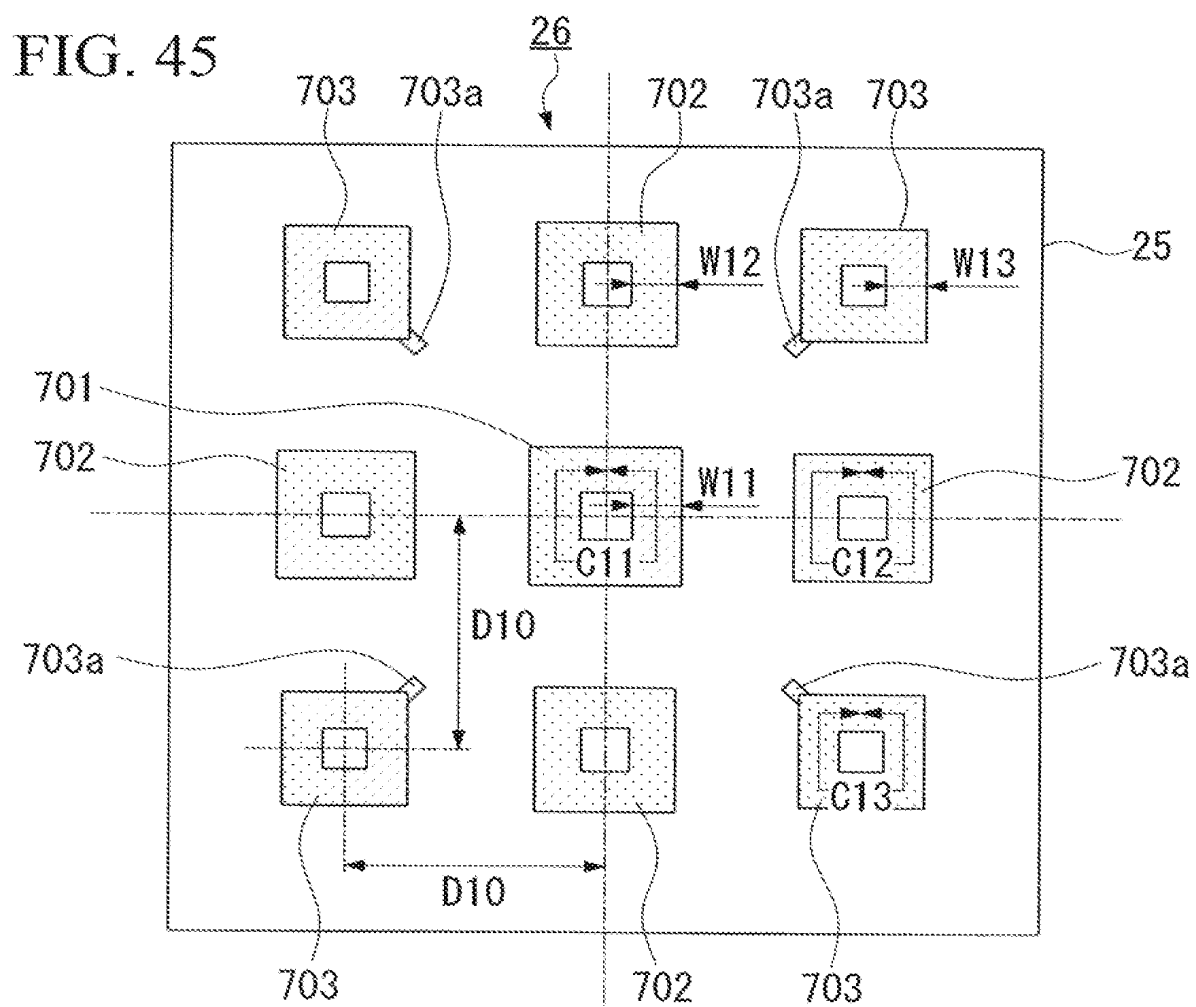
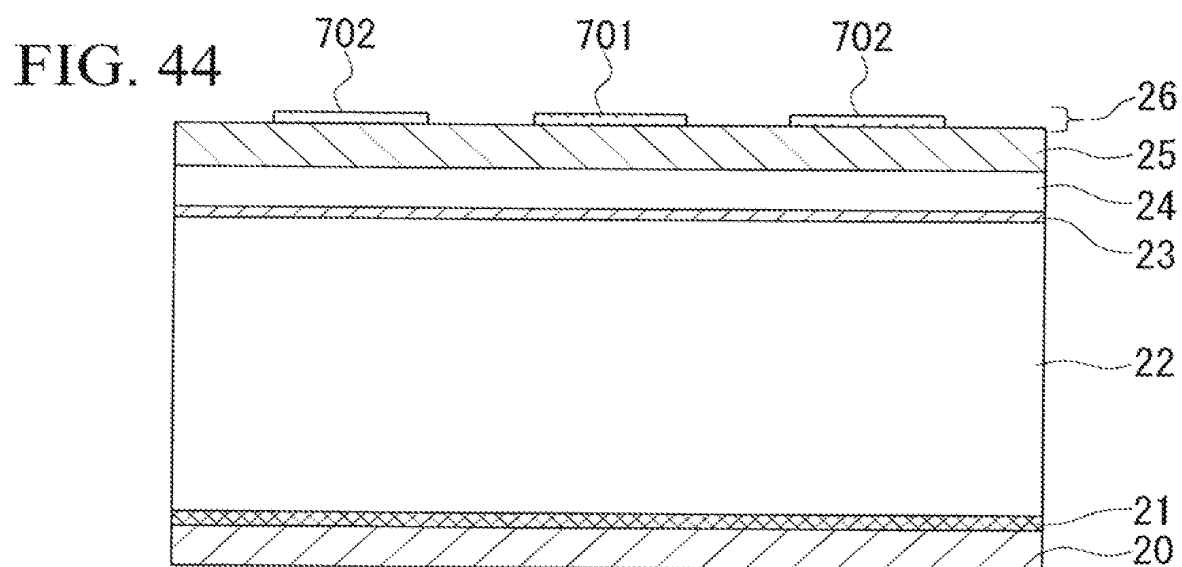
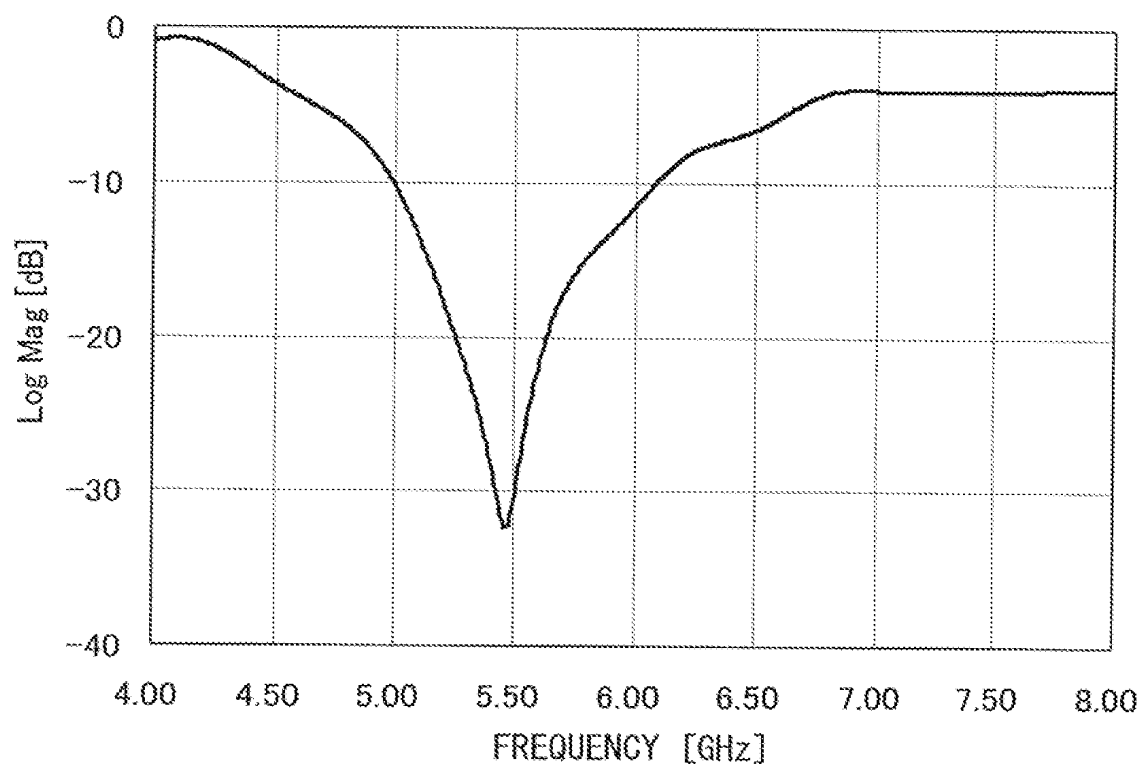


FIG. 46



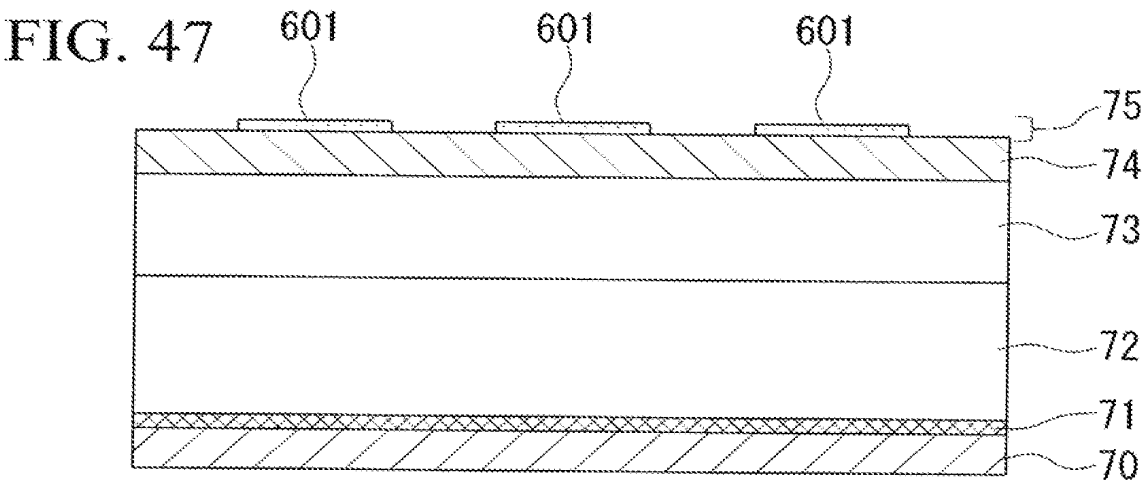
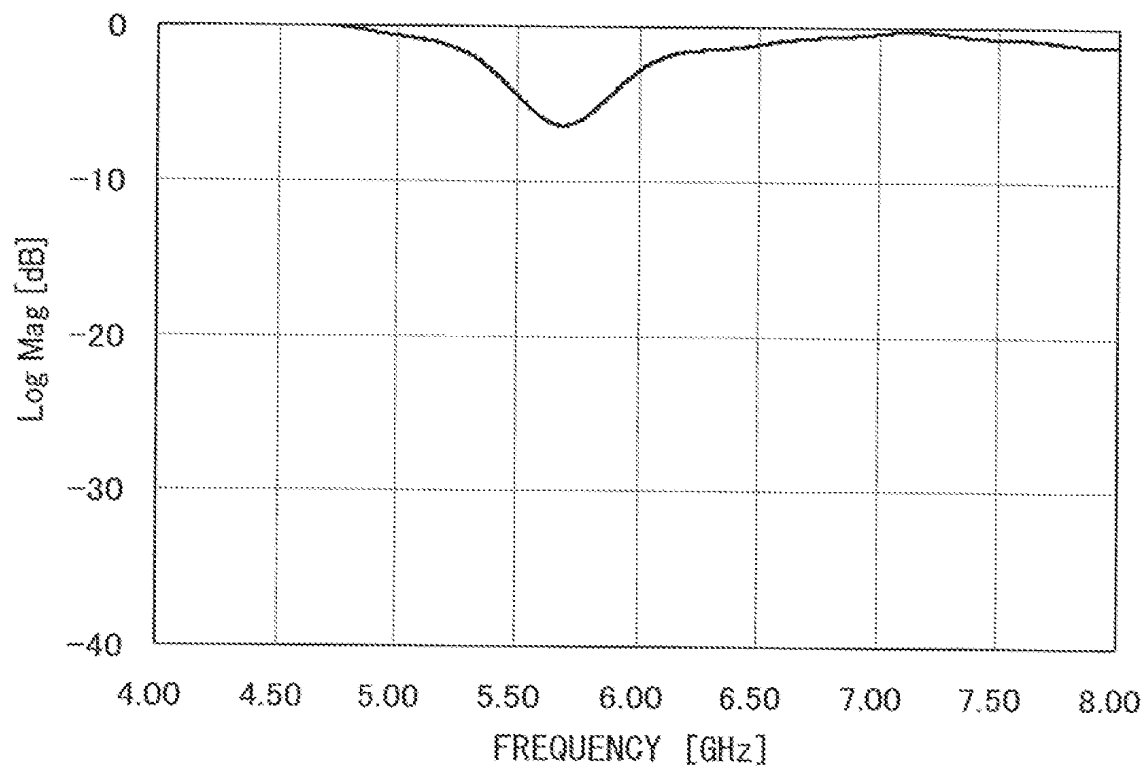


FIG. 48



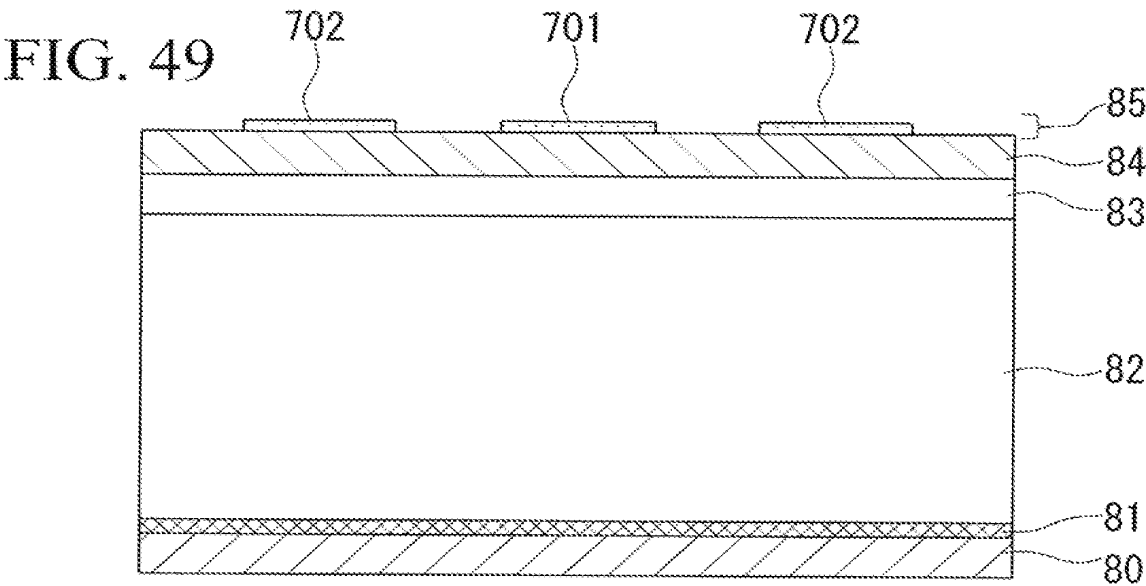


FIG. 50

